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# FDB8453LZ

## N-Channel PowerTrench<sup>®</sup> MOSFET

### 40V, 50A, 7.0mΩ

#### Features

- Max  $r_{DS(on)}$  = 7.0mΩ at  $V_{GS} = 10V$ ,  $I_D = 17.6A$
- Max  $r_{DS(on)}$  = 9.0mΩ at  $V_{GS} = 4.5V$ ,  $I_D = 14.9A$
- HBM ESD protection level of 7.6kV typical (note 4)
- Fast Switching
- RoHS Compliant

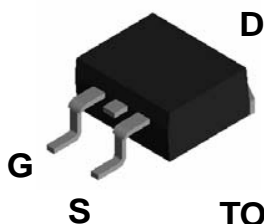


#### General Description

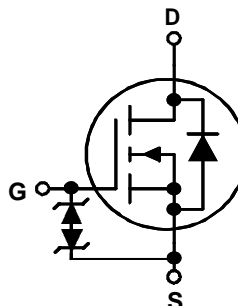
This N-Channel MOSFET is produced using Fairchild Semiconductor's advanced PowerTrench<sup>®</sup> process that has been especially tailored to minimize the on-state resistance and switching loss. G-S zener has been added to enhance ESD voltage level.

#### Applications

- Inverter
- Power Supplies



**TO-263AB**  
FDB Series



#### MOSFET Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Ratings	Units
$V_{DS}$	Drain to Source Voltage	40	V
$V_{GS}$	Gate to Source Voltage	±20	V
$I_D$	Drain Current -Continuous (Package limited) $T_C = 25^\circ\text{C}$	50	A
	-Continuous (Silicon limited) $T_C = 25^\circ\text{C}$	74	
	-Continuous $T_A = 25^\circ\text{C}$ (Note 1a)	16.1	
	-Pulsed	100	
$E_{AS}$	Single Pulse Avalanche Energy (Note 3)	253	mJ
$P_D$	Power Dissipation $T_C = 25^\circ\text{C}$	66	W
	Power Dissipation $T_A = 25^\circ\text{C}$ (Note 1a)	3.1	
$T_J, T_{STG}$	Operating and Storage Junction Temperature Range	-55 to +150	°C

#### Thermal Characteristics

$R_{\theta JC}$	Thermal Resistance, Junction to Case	1.88	°C/W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient (Note 1a)	40	

#### Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDB8453LZ	FDB8453LZ	TO-263AB	330mm	24mm	800 units

### Electrical Characteristics $T_J = 25^\circ\text{C}$ unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
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#### Off Characteristics

$BV_{DSS}$	Drain to Source Breakdown Voltage	$I_D = 250\mu\text{A}, V_{GS} = 0\text{V}$	40			V
$\frac{\Delta BV_{DSS}}{\Delta T_J}$	Breakdown Voltage Temperature Coefficient	$I_D = 250\mu\text{A}$ , referenced to $25^\circ\text{C}$		36		mV/ $^\circ\text{C}$
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 32\text{V}, V_{GS} = 0\text{V}$			1	$\mu\text{A}$
$I_{GSS}$	Gate to Source Leakage Current	$V_{GS} = \pm 20\text{V}, V_{DS} = 0\text{V}$			$\pm 10$	$\mu\text{A}$

#### On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_D = 250\mu\text{A}$	1.0	1.8	3.0	V
$\frac{\Delta V_{GS(th)}}{\Delta T_J}$	Gate to Source Threshold Voltage Temperature Coefficient	$I_D = 250\mu\text{A}$ , referenced to $25^\circ\text{C}$		-6.0		mV/ $^\circ\text{C}$
$r_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{V}, I_D = 17.6\text{A}$		6.3	7.0	m $\Omega$
		$V_{GS} = 4.5\text{V}, I_D = 14.9\text{A}$		7.3	9.0	
		$V_{GS} = 10\text{V}, I_D = 17.6\text{A}, T_J = 125^\circ\text{C}$		9.9	11	
$g_{FS}$	Forward Transconductance	$V_{DS} = 5\text{V}, I_D = 17.6\text{A}$		84		S

#### Dynamic Characteristics

$C_{iss}$	Input Capacitance	$V_{DS} = 20\text{V}, V_{GS} = 0\text{V}, f = 1\text{MHz}$		2665	3545	pF
$C_{oss}$	Output Capacitance			325	430	pF
$C_{rss}$	Reverse Transfer Capacitance			200	295	pF
$R_g$	Gate Resistance		$f = 1\text{MHz}$		2.2	

#### Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 20\text{V}, I_D = 17.6\text{A}, V_{GS} = 10\text{V}, R_{GEN} = 6\Omega$		11	20	ns	
$t_r$	Rise Time			6	13	ns	
$t_{d(off)}$	Turn-Off Delay Time			37	60	ns	
$t_f$	Fall Time			5	11	ns	
$Q_g$	Total Gate Charge		$V_{GS} = 0\text{V}$ to $10\text{V}$		47	66	nC
$Q_g$	Total Gate Charge	$V_{GS} = 0\text{V}$ to $5\text{V}$	$V_{DD} = 20\text{V}, I_D = 17.6\text{A}$		25	35	nC
$Q_{gs}$	Gate to Source Charge				7		nC
$Q_{gd}$	Gate to Drain "Miller" Charge				9		nC

#### Drain-Source Diode Characteristics

$V_{SD}$	Source to Drain Diode Forward Voltage	$V_{GS} = 0\text{V}, I_S = 2.6\text{A}$ (Note 2)		0.7	1.2	V
		$V_{GS} = 0\text{V}, I_S = 17.6\text{A}$ (Note 2)		0.8	1.3	
$t_{rr}$	Reverse Recovery Time	$I_F = 17.6\text{A}, di/dt = 100\text{A}/\mu\text{s}$		24	38	ns
$Q_{rr}$	Reverse Recovery Charge				15	27

#### Notes:

1:  $R_{\theta JA}$  is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins.  $R_{\theta JC}$  is guaranteed by design while  $R_{\theta JA}$  is determined by the user's board design.

- a.  $40^\circ\text{C}/\text{W}$  when mounted on a  $1\text{ in}^2$  pad of 2 oz copper
- b.  $62.5^\circ\text{C}/\text{W}$  when mounted on a minimum pad.

2: Pulse Test: Pulse Width  $< 300\mu\text{s}$ , Duty cycle  $< 2.0\%$ .

3: Starting  $T_J = 25^\circ\text{C}$ ,  $L = 3\text{mH}$ ,  $I_{AS} = 13\text{A}$ ,  $V_{DD} = 40\text{V}$ ,  $V_{GS} = 10\text{V}$ .

4: The diode connected between the gate and source serves only as protection against ESD. No gate overvoltage rating is implied.

**Typical Characteristics**  $T_J = 25^\circ\text{C}$  unless otherwise noted

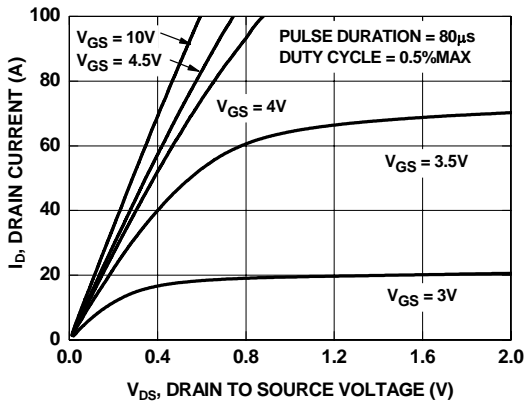


Figure 1. On-Region Characteristics

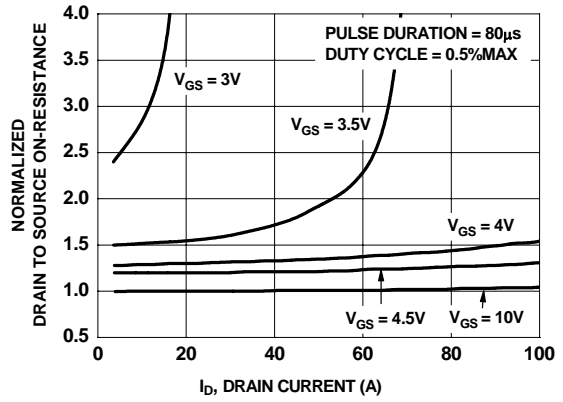


Figure 2. Normalized On-Resistance vs Drain Current and Gate Voltage

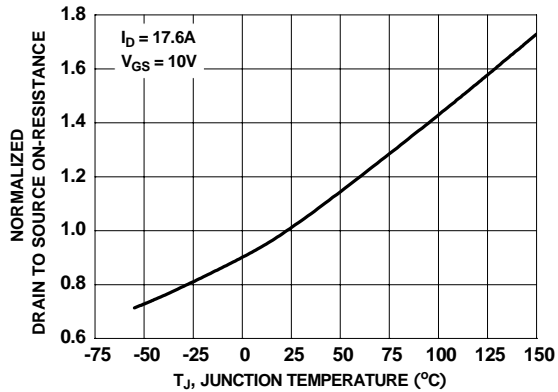


Figure 3. Normalized On-Resistance vs Junction Temperature

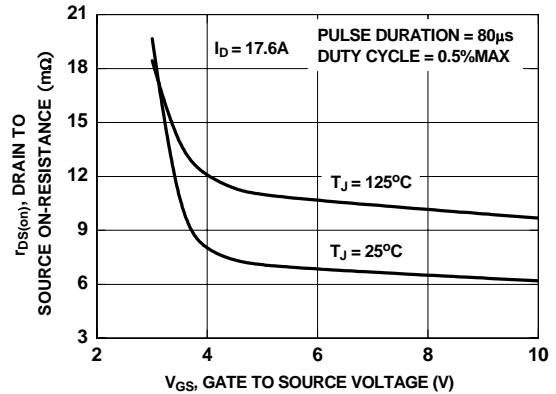


Figure 4. On-Resistance vs Gate to Source Voltage

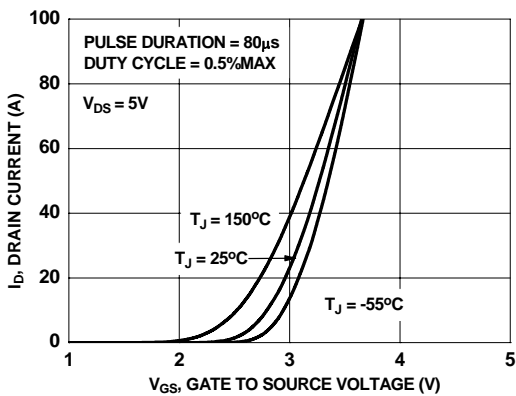


Figure 5. Transfer Characteristics

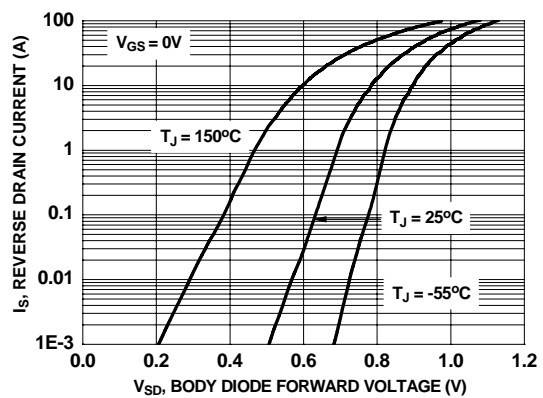
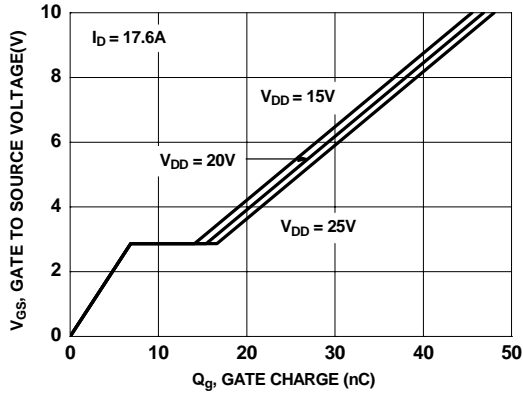
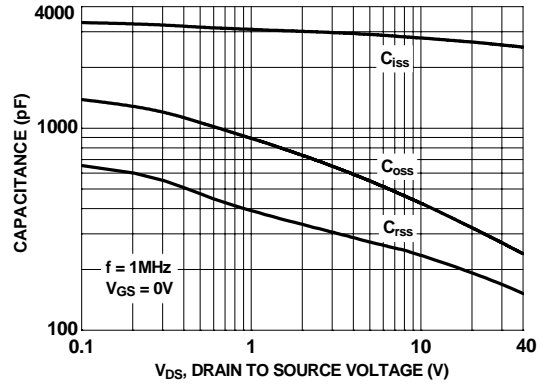


Figure 6. Source to Drain Diode Forward Voltage vs Source Current

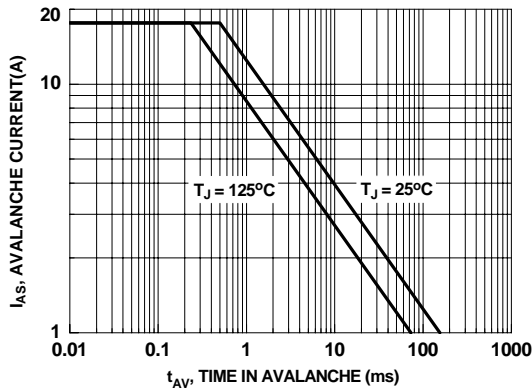
**Typical Characteristics**  $T_J = 25^\circ\text{C}$  unless otherwise noted



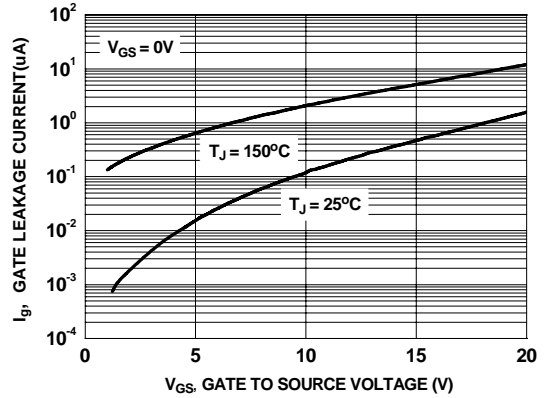
**Figure 7. Gate Charge Characteristics**



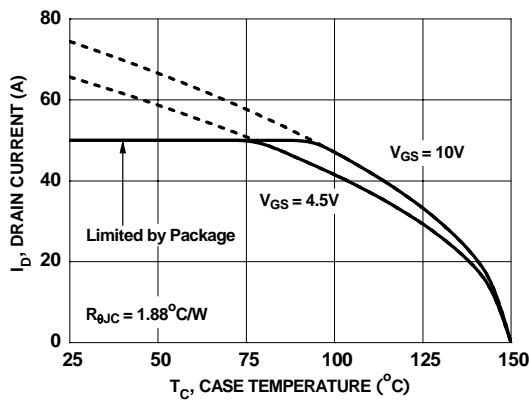
**Figure 8. Capacitance vs Drain to Source Voltage**



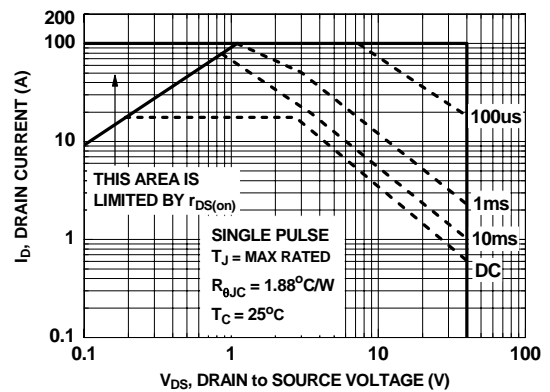
**Figure 9. Unclamped Inductive Switching Capability**



**Figure 10. Gate Leakage Current vs Gate to Source Voltage**

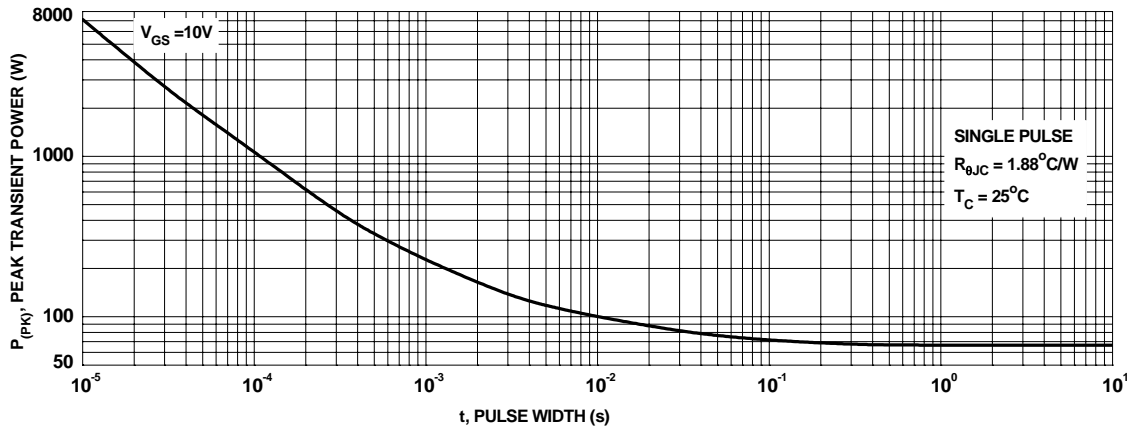


**Figure 11. Maximum Continuous Drain Current vs Ambient Temperature**

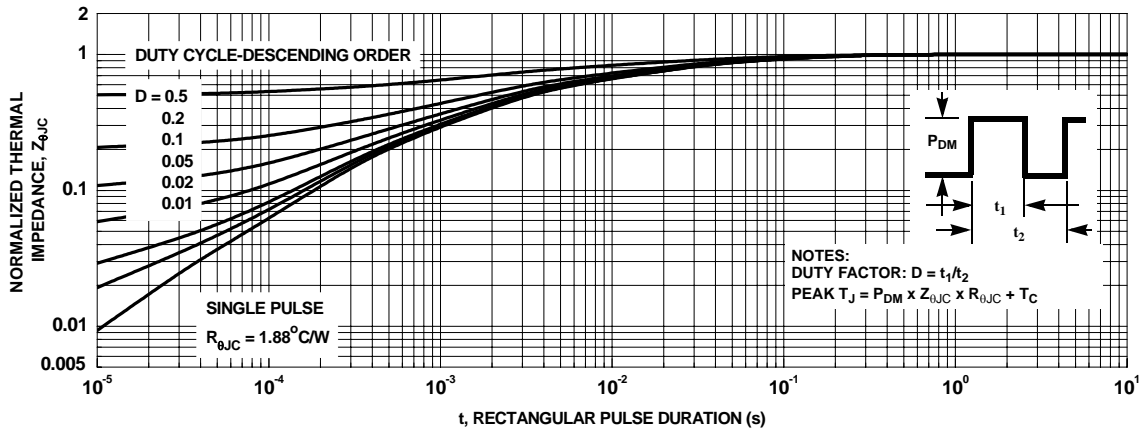


**Figure 12. Forward Bias Safe Operating Area**

**Typical Characteristics**  $T_J = 25^\circ\text{C}$  unless otherwise noted



**Figure 13. Single Pulse Maximum Power Dissipation**




**Figure 14. Transient Thermal Response Curve**



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